

Bondline 7081 is a thermally conductive epoxy adhesive that provides strong bonds to metals, such as gold, silver, copper, brass and solder.

*“A Reliable  
and Responsive  
Adhesive  
Company.”*

### Adhesive Properties

Color:	Blue
Viscosity*:	600,000 cps
Work Life @ 25°C:	4 hours
Hardness (Shore D):	90
Cure Options:	1 hour @ 120°C or 90 minutes @ 95°C or 4 hours @ 75°C
Service Temperature Range:	-55°C to 150°C
Glass Transition Temperature (Tg)**:	102°C
Lap Shear Strength @ 25°C (Al to Al):	3200 psi
Weight Loss (TGA) @ 200°C:	0.07%
Specific Gravity:	2.1
Thermal Conductivity @ 121°C:	0.9 Btu ft <sup>-1</sup> hour <sup>-1</sup> F <sup>-1</sup>
Dielectric Strength:	500 volts/mil
Coefficient of Thermal Expansion:	
Below Tg:	92 x 10 <sup>-6</sup> in/in/°C
Above Tg:	105 x 10 <sup>-6</sup> in/in/°C
Shelf Life:	1 year @ -40°C or Colder
Availability:	Net volume 1cc to 10cc, available in disposable 3cc, 5cc & 10cc syringes.

Adhesive properties are not intended to be used as specification limits.

\* Brookfield DVII+ (Cone & Plate), 51 Spindle, 0.5 rpm, 25°C

\*\* Cured 90 minutes @ 95°C

**Bondline™**

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